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Sheet 1 of 1

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INFORMATION DISCLOSURE STATEMENT
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Applicant: Leonard Forbes et al.

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Filing Date: July 29, 1997

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Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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JK	Zirinsky, S., et al., "Electrical Resistivity of Amorphous Silicon Resistor Films", <u>Extended Abstracts of the Spring Meeting of the Electrochemical Society</u> , Washington, DC, pp. 147-149, (1971)

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Examiner JL Ebert Date Considered 5/19/01

*Substitute Disclosure Statement Form (PTO-1449)

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